

REMARKS

Claims 1-17 are all the claims pending in the application. As shown in the foregoing amendments, claims 1, 10 and 11 are amended. Subject matter from dependent claim 10 has been incorporated into independent claims 1 and 11. Thus, it is believed that new matter has not been added such that additional search and/or consideration would be required. Accordingly, Applicant respectfully requests withdrawal of the rejection, and allowance of the claims.

Claims 1-17 stand rejected due to alleged obviousness under 35 U.S.C. § 103(a) over the Examiner's proposed combination of Spenadel and Maxfield. Applicant respectfully submits that the Examiner's proposed combination of references fails to teach or suggest all of the claimed combinations of features. For at least the reasons herein, Applicant respectfully requests withdrawal of the rejection, and allowance of the claims.

Applicant notes that the presently claimed invention is directed to direct current power cables having a medium to high voltage. More specifically, Applicant refers the Examiner to the DC cable in application page 6, lines 30 to 37: "the mechanism of forming the nanocomposite material and extruding it encourages an orientation of the organic compound which limits migration of space charges; nanocomposite material improves the resistance of the cable to breakdown in the event of a change of polarity".

Further, Applicant respectfully submits that the claimed power cable is not disclosed or suggested in the cited art of record. For example, but not by way of limitation, Applicant respectfully submits that the prior art of record fails to disclose or suggest that the power cable is a medium to high voltage power cable, as recited in independent claims 1 and 11.

More specifically, Spenadel is directed to a low-medium voltage cable as disclosed at (), in distinction to the claimed medium-high voltage cable. Thus, Spenadel does not disclose all of the features recited in the independent claims. To cure this deficiency, it is proposed that Maxfield be combined with Spenadel.

Applicant respectfully submits that Maxfield discloses only as example of molded articles, “components for the electrical and electronics industries”. There is no specific disclosure of a medium-high voltage DC power cable. Further, Applicant respectfully submits that one skilled in the art would not understand Maxfield to be directed to the claimed power cable, because the disclosed uses of Maxfield do not appear to be for medium to high voltage DC cables.

Applicant respectfully submits that Maxfield fails to cure to above-noted deficiency of Spenadel with respect to the claims. Thus, it is submitted that the proposed combination of references fails to disclose or suggest a medium-high voltage DC cable, as recited in independent claims 1 and 11.

Additionally, Applicant respectfully submits that one skilled in the art would not have been motivated to combine Spenadel and Maxfield to produce the claimed invention. As noted above, Spenadel is specifically directed to a cable that is configured to carry a much lower voltage than that claimed invention. Applicant respectfully submits that to run a higher voltage through such a cable would render it inoperable for its principle purpose. Further, there is no disclosure of a medium-high voltage in Maxfield, and thus, the combination does not cure this deficiency. Accordingly, Applicant respectfully submits that the combination is improper, and respectfully requests its withdrawal.

Amendment Under 37 C.F.R. § 1.116
U.S. Appln. No. 09/673,143

Dependent claims 2-10 and 12-17 depend from independent claims 1 and 11, respectively. Applicant respectfully submits that the dependent claims are allowable for at least the same reasons as discussed above with respect to the independent claims from which they depend. Therefore, Applicant respectfully requests withdrawal of the rejection, and allowance of the claims.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



Mainak H. Mehta
Registration No. 46,924

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE



23373

PATENT TRADEMARK OFFICE

Date: June 13, 2003

APPENDIX
VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

The claims are amended as follows:

1. (Four times amended) A power cable comprising:

a conductive material core; and

at least one covering layer, characterized in that said at least one covering layer is constituted essentially of a material comprising an inorganic compound made from a nanocomposite material and an organic compound positioned between layers of said inorganic compound, wherein the power cable is a medium-voltage to high voltage direct current power cable.

10. (Three times amended) [A medium-voltage to high-voltage direct current]The power cable according to claim 1, wherein the at least one covering layer comprises at least one semiconductor screen, characterized in that the at least one semiconductor screen is constituted essentially of a material comprising an inorganic compound having an exfoliated layered structure and an organic compound inserted between the layers of said inorganic compound.

11. (Twice Amended) A method of fabricating at least one conductive layer of a medium-voltage to high voltage direct current power cable having a conductive core, comprising the following steps:

treating layers of an inorganic compound with an agent to render said inorganic compound compatible with an organic compound;

inserting said organic compound between said layers of said inorganic compound at a

Amendment Under 37 C.F.R. § 1.116
U.S. Appl. No. 09/673,143

temperature higher than the temperature at which said organic compound softens or melts to exfoliate said inorganic compound; and

obtaining a material with said organic compound inserted between the layers of said inorganic compound.